Appendix A

2. (Amended) The hot plate according to claim 1, characterized in that the conductive layer <u>further</u> includes [ruthenium oxide,] bismuth or its oxide [, glass frit, and noble metal grains].

3. (Amended) The hot plate according to claim 1 [or 2], characterized in that the ceramic substrate is a ceramic substrate is a ceramic nitride substrate or a ceramic carbide base plate.

4. (Amended) The hot plate according to [any one of claims 1 to 3] <u>claim 1</u>, wherein the glass frit includes zinc boron silicate.

5. (Amended) The hot plate according to [any one of claims 1 to 4] <u>claim 1</u>, wherein the noble metal grains is at least one selected from gold grains, silver grains, platinum grains, and palladium grains.

8. (New) A hot plate that uses a ceramic substrate provided with a conductive layer, wherein the hot plate characterized in that the conductive layer includes ruthenium oxide, bismuth or its oxide, glass frit, and noble metal grains, wherein the ceramic substrate is a ceramic nitride substrate or a ceramic carbide base plate..

9. (New) The hot plate according to claim 8 , wherein the glass frit includes zinc boron silicate.

10. (New) The hotplate according to claim 8, wherein the noble metal grains is at least one selected from gold grains, silver grains, platinum grains, and palladium grains.

11. (New) The hot plate according to claim 10, wherein the glass frit includes zinc boron silicate.